



PRODUCT DATASHEET



- DC Input Photo Coupler
- Random-Phase TRIAC

SMD6 Low Profile

TD302X(SL)(T1)-GV





APPLICATIONS:

- Solenoid/valve controls
- Lighting controls
- Motor controls
- Temperature controls
- Static AC power switches
- Solid state relays
- Interfacing microprocessors to 115 to 240VAC peripherals

TD302X(SL) Series

DESCRIPTION:

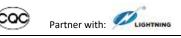


The TD302X(SL) series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a monolithic silicon random-phase photo TRIAC in a plastic DIP6 package with SMD6 Low Profile lead forming option.

With the robust coplanar double mold structure, TD302X(SL) series provide the most stable isolation feature.

FEATURES:

- High isolation 5000Vrms
- DC input with random-phase photo TRIAC output
- Operating temperature range -40°C to +100°C
- REACH & RoHS compliance
- MSL class 1
- Regulatory Approvals:
 - o UL UL1577
 - o VDE EN60747-5-5 (VDE0884-5)
 - o CQC GB4943.1, GB8898
 - o cUL CSA Component Acceptance Service Notice 5A
- Packing: 1000pcs/reel



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Naming Information:

TD302 X (SL) (T1) - G V				
TD302X	Part Number			
×	Selection: LED Trigger Current (X=1~3)			
SL	Lead Form Option: SMD6 Low Profile			
τ1	Selection: Tape and Reel Option (T1(default)/T2)			
G	Green Option			
V	VDE Option			

Ordering Information:

TD302 <u>X</u> (SL)(T1)-GV						
	\underline{X} = Selection: LED Trigger Current (X=1~3)					
Part Number	Symbol	Values			Unit	Test Condition
	Symbol	Min.	Тур.	Max.	Onit	
TD3021(SL)(T1)-GV				15		L =100m A
TD3022(SL)(T1)-GV	IFT			10	mA	I _™ =100mA Terminal Voltage=3V
TD3023(SL)(T1)-GV				5		voitage-3v

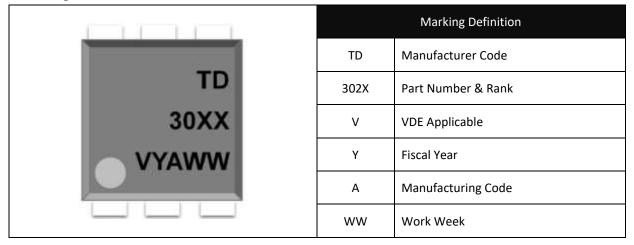
Version No.	Original Release Date
Rev: A00	05/09/2024



SCHEMATIC DIAGRAM & MARKING:

Schematic Diagram: **PIN Definition** 1 Anode 1 2 Cathode NC 2 3 4 Terminal 3 5 Substrate 6 Terminal

Marking Information:



Labelling Information:





Absolute Maximum Ratings:

Parameter	Symbol	Ratings	Unit			
INPUT						
Forward Current	IF	60	mA			
Reverse Voltage	V _R	6	V			
Junction Temperature	Tj	125	°C			
Input Power Dissipation	Pı	100	mW			
	OUTPUT					
Off-State Output Terminal Voltage	Vdrm	400	V			
Peak Repetitive Surge Current PW=100μs, 120pps	Ітѕм	1	А			
On-State RMS Current	It(rms)	100	mA			
Junction Temperature	Tj	125	°C			
Output Power Dissipation	Po	300	mW			
COMMON						
Total Power Dissipation	P _{tot}	400	mW			
Isolation Voltage	Viso	5000 ^{*1}	Vrms			
Operating Temperature	T _{opr}	-40~+100	°C			
Storage Temperature	T _{stg}	-55~+125	°C			
Soldering Temperature	T _{sol}	260 ^{*2}	°C			

*1. AC for 1 minute, R.H.=40~60%.

*2. For 10 seconds max.



ELECTRICAL CHARACTERISTICS:

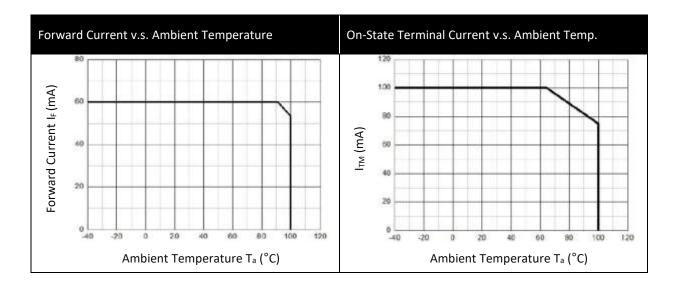
Electrical Optical Characteristics at T _a =25°C:

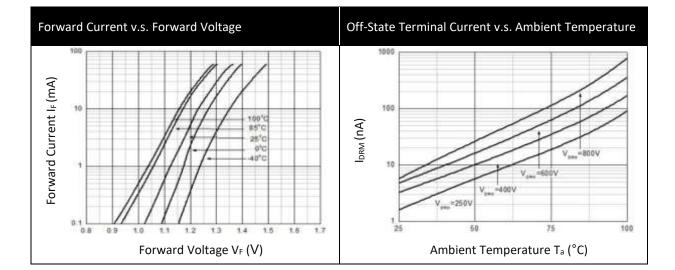
Parameter		Symbol	Values			Unit	Test Condition
		Symbol	Min.	Тур.	Max.	Unit	rest condition
INPUT							
Forward Voltage		V _F		1.24	1.4	V	I _F =10mA
Reverse Current		I _R			10	μΑ	V _R =6V
Input Capacitance		Cin		8.5	250	pF	V=0, f=1kHz
			OUTPL	JT			
Peak Off-State Curren Either Direction	nt	Idrm			100 *1	nA	V_{DRM} =Rated V_{DRM} I _F =0
Peak On-State Voltag Either Direction	e	V _{TM}		1.58	2.5	V	I _{TM} =100mA
Critical Rate of Rise of Off-State Voltage		dV/dt	1000			V/µs	V _{PEAK} =400V I _F =0
	TRANSFER CHARACTERISTICS						
	TD3021				15		Iтм=100mA
LED Trigger Current	TD3022	IFT			10	mA	Terminal Voltage=3V
	TD3023				5		
Holding Current		Ін		257		μΑ	
Isolation Resistance R _{IS}		R _{ISO}	10^12	10^14		Ω	DC=500V, 40~60% R.H.
Floating Capacitance		Cio		0.8		рF	V=0, f=1MHz

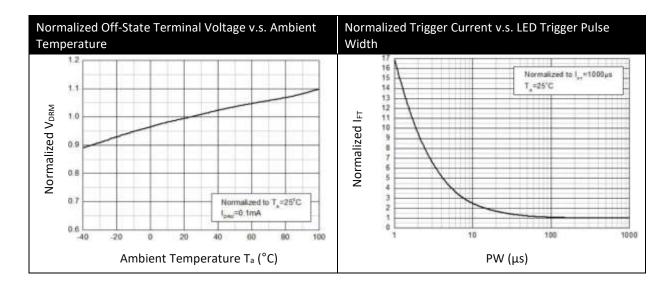
*1. Test voltage must be applied within dV/dt rating.



CHARACTERISTIC CURVES:

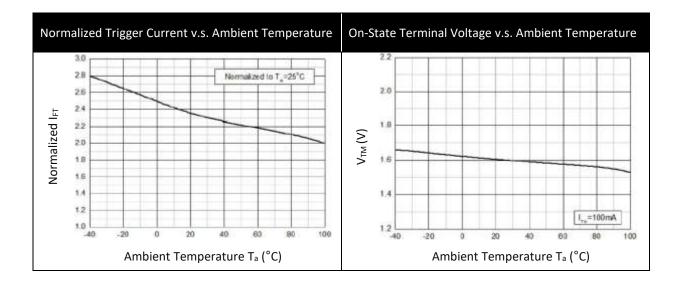


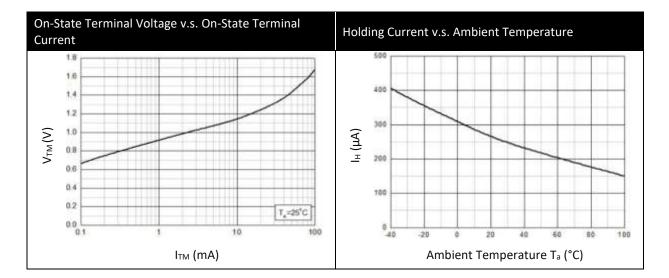


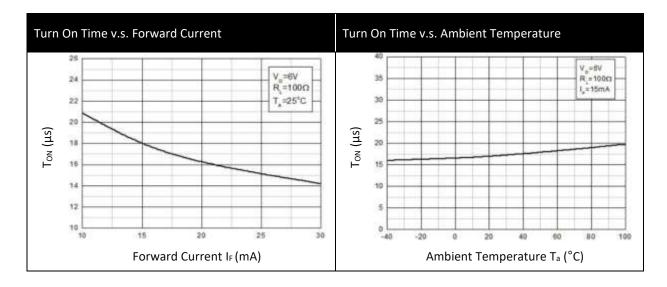




CHARACTERISTIC CURVES:



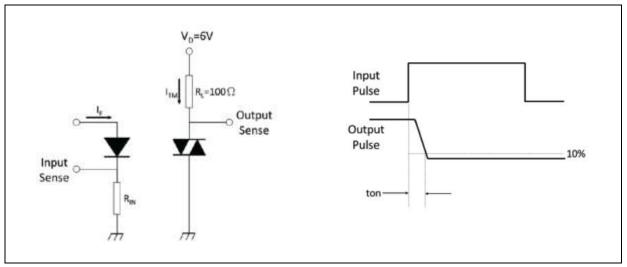




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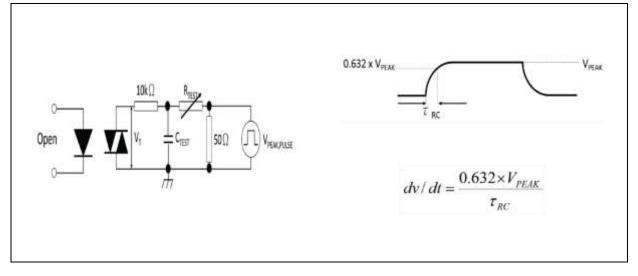


TEST CIRCUIT:



Test Circuit and Waveforms of Turn On Time:

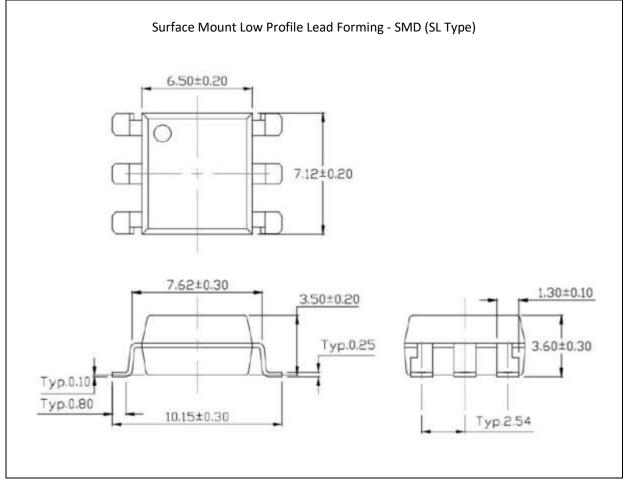
Test Circuit and Waveforms of dV/dt:





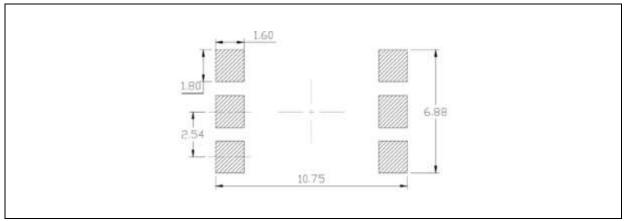
OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).

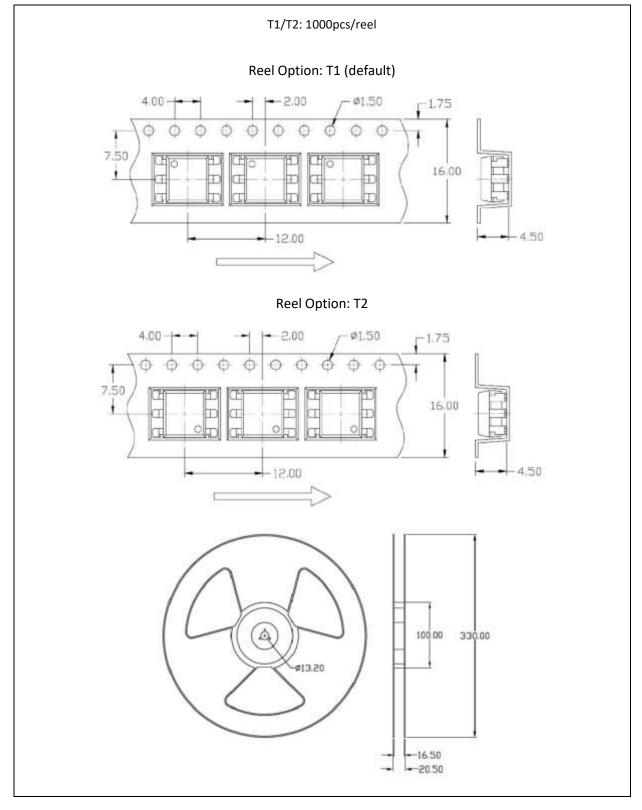
Recommended Soldering Mask:



1. Dimensions are in millimetre (mm).



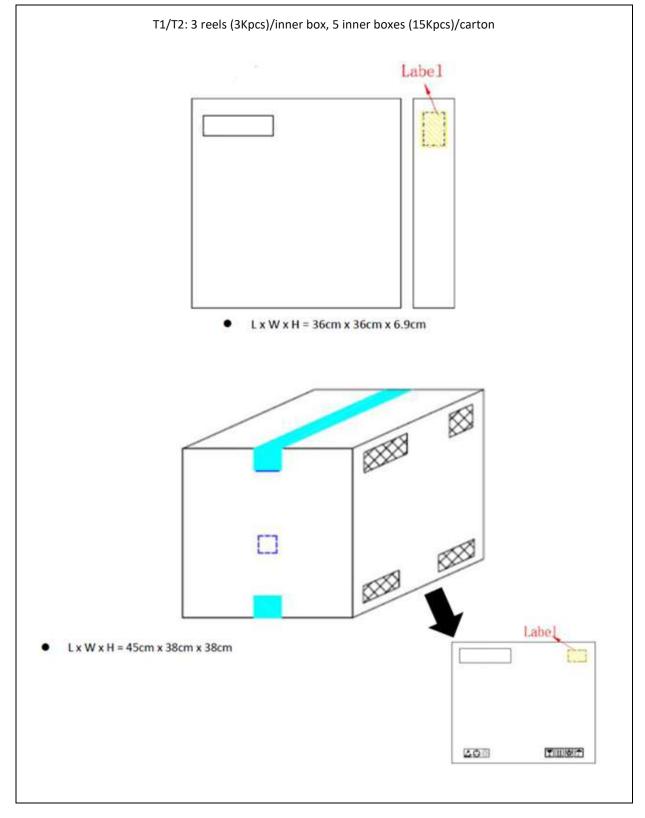
Reel Dimension:





PACKING SPECIFICATION:

Box Dimension:





RECOMMENDED SOLDERING PROFILE:

Reflow Information:

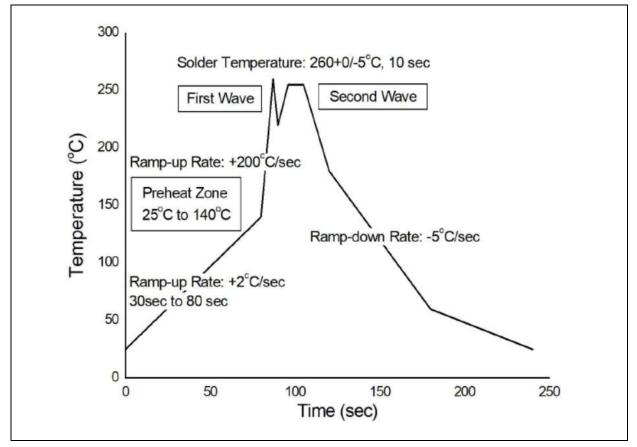
Г

Supplier T _p 2	T_c Us T_c T_c T	er $T_p \leq T_c$
	amp Up Rate = 3°C/s amp Down Rate = 6°C/s	t _p → T _c -5°C
Time 25°C to		+
← Time 25°C to	Time ⇔	Pb-Free Assembly Profile
← Time 25°C to Profile Feature		Pb-Free Assembly Profile 150°C
← Time 25°C to	Time → Sn-Pb Assembly Profile	Pb-Free Assembly Profile
← Time 25°C to Profile Feature Temperature Min. (T _{smin})	Time → Sn-Pb Assembly Profile 100°C	Pb-Free Assembly Profile 150°C
← Time 25°C to Profile Feature Temperature Min. (T _{smin}) Temperature Max. (T _{smax})	Time → Sn-Pb Assembly Profile 100°C 150°C	Pb-Free Assembly Profile 150°C 200°C
Time 25°C to Profile Feature Temperature Min. (T _{smin}) Temperature Max. (T _{smax}) Time (t _s) from (T _{smin} to T _{smax})	Time → Sn-Pb Assembly Profile 100°C 150°C 60-120 seconds	Pb-Free Assembly Profile 150°C 200°C 60-120 seconds
Frofile Feature Profile Feature Temperature Min. (Tsmin) Temperature Max. (Tsmax) Time (ts) from (Tsmin to Tsmax) Ramp-up Rate (tL to tP)	Time → Sn-Pb Assembly Profile 100°C 150°C 60-120 seconds 3°C/second max.	Pb-Free Assembly Profile 150°C 200°C 60-120 seconds 3°C/second max.
Frofile Feature Profile Feature Temperature Min. (Tsmin) Temperature Max. (Tsmax) Time (ts) from (Tsmin to Tsmax) Ramp-up Rate (tL to tP) Liquidous Temperature (TL)	Time Sn-Pb Assembly Profile 100°C 150°C 60-120 seconds 3°C/second max. 183°C	Pb-Free Assembly Profile 150°C 200°C 60-120 seconds 3°C/second max. 217°C
Frofile Feature Profile Feature Temperature Min. (Tsmin) Temperature Max. (Tsmax) Time (ts) from (Tsmin to Tsmax) Ramp-up Rate (tL to tP) Liquidous Temperature (TL) Time (tL) Maintained Above (TL)	Time Sn-Pb Assembly Profile 100°C 150°C 60-120 seconds 3°C/second max. 183°C 60-150 seconds	Pb-Free Assembly Profile 150°C 200°C 60-120 seconds 3°C/second max. 217°C 60-150 seconds
Frofile Feature Profile Feature Temperature Min. (Tsmin) Temperature Max. (Tsmax) Time (ts) from (Tsmin to Tsmax) Ramp-up Rate (tL to tP) Liquidous Temperature (TL) Time (tL) Maintained Above (TL) Peak Body Package Temperature	Time Sn-Pb Assembly Profile 100°C 150°C 60-120 seconds 3°C/second max. 183°C 60-150 seconds 235°C +0°C / -5°C	Pb-Free Assembly Profile 150°C 200°C 60-120 seconds 3°C/second max. 217°C 60-150 seconds 260°C +0°C / -5°C



RECOMMENDED SOLDERING PROFILE:

Wave Soldering (JESD22-A111 Compliant):



Hand Soldering:

Soldering Temperature	380±5°C
Soldering Time	3 sec max.

Note:

- One time soldering is recommended for all soldering methods.
- Do not solder more than three times for IR reflow soldering.